DATA SHEET

74LVC14A

Hex inverting Schmitt-trigger with 5V tolerant input

Product specification

1998 Apr 28

Philips
Semiconductors

PHILIPS

Hex inverting Schmitt-trigger with 5V tolerant input

74LVC14A

FEATURES

- Wide supply voltage range of: 1.2 V to 3.6 V
- In accordance with JEDEC standard no. 8-1A
- Inputs accept voltages up to 5.5 V
- CMOS low power consumption
- Direct interface with TTL levels

APPLICATIONS

- Wave and pulse shapers for highly noisy environments
- Astable multivibrators
- Monostable multivibrators

DESCRIPTION

The 74LVC14A is a high-performance, low power, low-voltage Si-gate CMOS device and superior to most advanced CMOS compatible TTL families.

Inputs can be driven from either 3.3 V or 5 V devices. This feature allows the use of these devices as translators in a mixed 3.3 V/5 V environment.

The 74LVC14A provides six inverting buffers with Schmitt-trigger action. It is capable of transforming slowly changing input signals into sharply defined, jitter-free output signals.

QUICK REFERENCE DATA

GND = 0 V; T_{amb} = 25°C; $t_r \leq t_f \leq 2.5$ ns

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t_{PHL}/t_{PLH}	Propagation delay nA to nY	C_L = 50 pF; V_{CC} = 3.3 V	4	ns
C_I	Input capacitance		3.5	pF
C_{PD}	Power dissipation capacitance per gate	Notes 1 and 2	25	pF

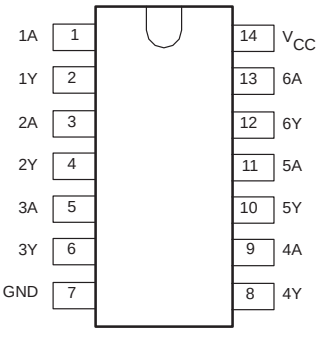
NOTES:

1. C_{PD} is used to determine the dynamic power dissipation (P_D in μW)
   $P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$ where:
   f_i = input frequency in MHz; C_L = output load capacity in pF;
   f_o = output frequency in MHz; V_{CC} = supply voltage in V;
   $\sum (C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.
2. The condition is V_I = GND to V_{CC}.

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
14-Pin Plastic SO	–40°C to +85°C	74LVC14A D	74LVC14A D	SOT108-1
14-Pin Plastic SSOP Type II	–40°C to +85°C	74LVC14A DB	74LVC14A DB	SOT337-1
14-Pin Plastic TSSOP Type I	–40°C to +85°C	74LVC14A PW	74LVC14APW DH	SOT402-1

PIN CONFIGURATION

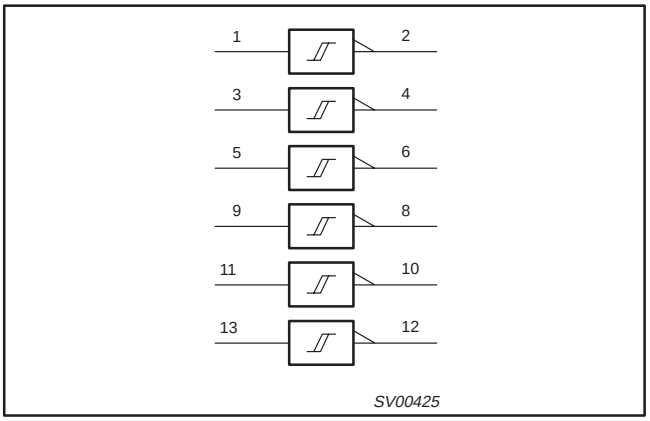


SV00396

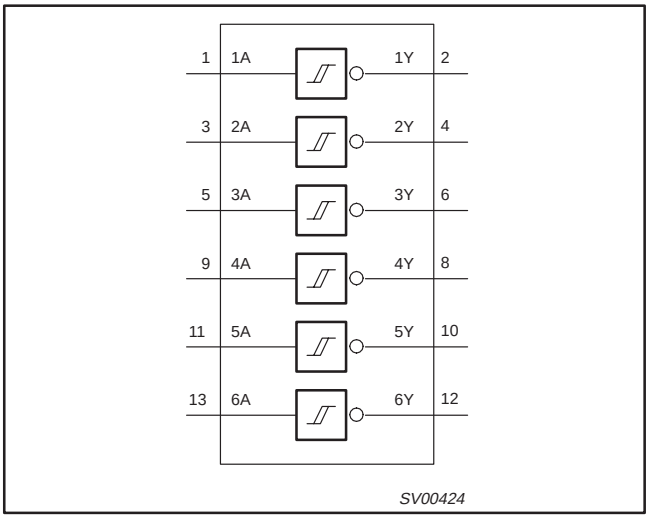
PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
1, 3, 5, 9, 11, 13	1A – 6A	Data inputs
2, 4, 6, 8, 10, 12	1Y – 6Y	Data outputs
7	GND	Ground (0 V)
14	V_{CC}	Positive supply voltage

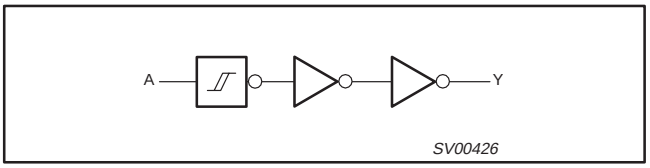
LOGIC SYMBOL (IEEE/IEC)



LOGIC SYMBOL



LOGIC DIAGRAM (ONE SCHMITT-TRIGGER)



FUNCTION TABLE

INPUT	OUTPUT
nA	**nY**
L	H
H	L

NOTES:
H = HIGH voltage level
L = LOW voltage level

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	LIMITS		UNIT
			MIN	MAX	
V_{CC}	DC supply voltage (for max. speed performance)		2.7	3.6	V
	DC supply voltage (for low-voltage applications)		1.2	3.6	
V_I	DC input voltage range		0	5.5	V
$V_{I/O}$	DC output voltage range; output HIGH or LOW state		0	V_{CC}	V
	DC input voltage range; output 3-State		0	5.5	
T_{amb}	Operating free-air temperature range		–40	+85	°C
t_r, t_f	Input rise and fall times	V_{CC} = 1.2 to 2.7V V_{CC} = 2.7 to 3.6V	0 0	20 10	ns/V

ABSOLUTE MAXIMUM RATINGS[1]

In accordance with the Absolute Maximum Rating System (IEC 134).
Voltages are referenced to GND (ground = 0V).

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V_{CC}	DC supply voltage		–0.5 to +6.5	V
I_{IK}	DC input diode current	$V_I < 0$	–50	mA
V_I	DC input voltage	Note 2	–0.5 to +6.5	V
I_{OK}	DC output diode current	$V_O > V_{CC}$ or $V_O < 0$	±50	mA
$V_{I/O}$	DC output voltage; output HIGH or LOW	Note 2	–0.5 to V_{CC} +0.5	V
	DC input voltage; output 3-State	Note 2	–0.5 to 6.5	
I_O	DC output source or sink current	V_O = 0 to V_{CC}	±50	mA
I_{GND}, I_{CC}	DC V_{CC} or GND current		±100	mA
T_{stg}	Storage temperature range		–65 to +150	°C
P_{TOT}	Power dissipation per package			mW
	– plastic mini-pack (SO)	above +70°C derate linearly with 8 mW/K	500	
	– plastic shrink mini-pack (SSOP and TSSOP)	above +60°C derate linearly with 5.5 mW/K	500	

NOTES:
1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
2. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions. Voltages are referenced to GND (ground = 0V).

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS			UNIT
			Temp = -40°C to +85°C			
			MIN	TYP[1]	MAX	
V_{IH}	HIGH level Input voltage	V_{CC} = 1.2V	V_{CC}			V
		V_{CC} = 2.7 to 3.6V	2.0			
V_{IL}	LOW level Input voltage	V_{CC} = 1.2V			GND	V
		V_{CC} = 2.7 to 3.6V			0.8	
V_{OH}	HIGH level output voltage	V_{CC} = 2.7V; $V_I = V_{IH}$ or V_{IL}; I_O = –12mA	V_{CC} – 0.5			V
		V_{CC} = 3.0V; $V_I = V_{IH}$ or V_{IL}; I_O = –100µA	V_{CC} – 0.2	V_{CC}		
		V_{CC} = 3.0V; $V_I = V_{IH}$ or $V_{IL;}$ I_O = –18mA	V_{CC} – 0.6			
		V_{CC} = 3.0V; $V_I = V_{IH}$ or $V_{IL;}$ I_O = –24mA	V_{CC} – 0.8			
V_{OL}	LOW level output voltage	V_{CC} = 2.7V; $V_I = V_{IH}$ or V_{IL}; I_O = 12mA			0.40	V
		V_{CC} = 3.0V; $V_I = V_{IH}$ or V_{IL}; I_O = 100µA		GND	0.20	
		V_{CC} = 3.0V; $V_I = V_{IH}$ or $V_{IL;}$ I_O = 24mA			0.55	
I_I	Input leakage current	V_{CC} = 3.6V; V_I = 5.5V or GND		±0.1	±5	µA
I_{CC}	Quiescent supply current	V_{CC} = 3.6V; $V_I = V_{CC}$ or GND; I_O = 0		0.1	10	µA
ΔI_{CC}	Additional quiescent supply current per input pin	V_{CC} = 2.3V to 3.6V; $V_I = V_{CC}$ –0.6V; I_O = 0		5	500	µA

NOTE:
1. All typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.

TRANSFER CHARACTERISTICS

Voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	T_{amb} (°C)			UNIT	TEST CONDITIONS	
		–40 TO +85				V_{CC} (V)	WAVEFORMS
		MIN	TYP[1]	MAX			
V_{T+}	Positive-going threshold	–	–	1.2	V	1.2	Figures 1 and 2
		1.1	–	2.0		2.7	
		1.1	–	2.0		2.7 to 3.6	
V_{T-}	Negative-going threshold	0	–	–	V	1.2	Figures 1 and 2
		0.8	–	1.5		2.7	
		0.8	–	1.5		2.7 to 3.6	
V_H	Hysteresis ($V_{T+} - V_{T-}$)	–	–	–	V	1.2	Figures 1, 2 and 3
		0.3	0.4	–		2.7	
		0.3	0.45*	–		2.7 to 3.6	

NOTES:
1. All typical values are measured at T_{amb} = 25°C
2. The V_{IH} and V_{IL} from the DC family characteristics are superseded by the V_{T+} and V_{T-}.

TRANSFER CHARACTERISTIC WAVEFORMS

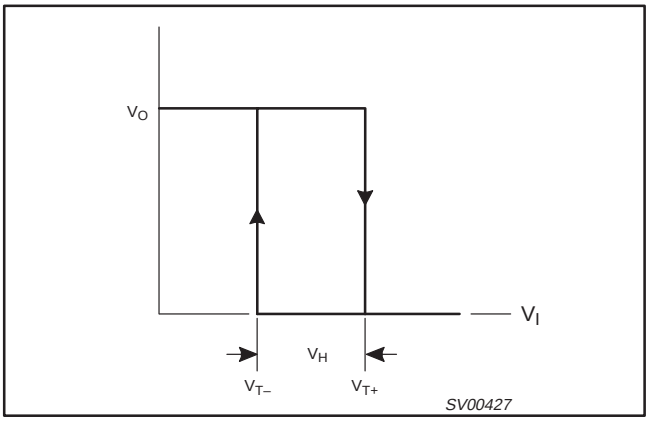


Figure 1. Transfer characteristic.

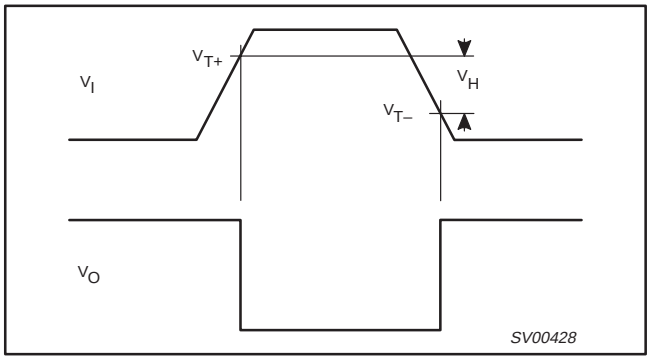


Figure 2. Definition of V_{T+}, V_{T-} and V_H; where V_{T+} and V_{T-} are between limits of 20% and 70%

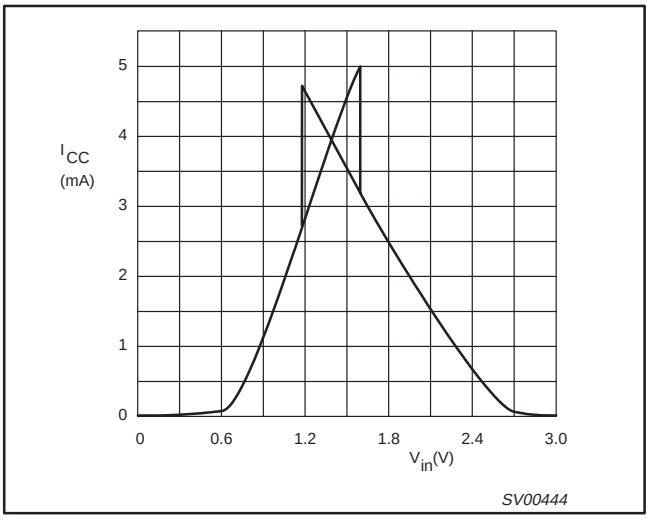


Figure 3. Typical 74LVC14 transfer characteristics; V_{CC} = 3.3 V.

AC CHARACTERISTICS

GND = 0 V; $t_r = t_f \leq 2.5$ ns; $C_L = 50$ pF; $R_L = 500\Omega$; $T_{amb} = -40°C$ to $+85°C$

SYMBOL	PARAMETER	WAVEFORM	LIMITS							UNIT
			V_{CC} = 3.3V ±0.3V			V_{CC} = 2.7V			V_{CC} = 1.2V	
			MIN	TYP[1]	MAX	MIN	TYP	MAX	TYP	
t_{PHL}/ t_{PLH}	Propagation delay nA to nY	Figure 1, 2	1.5	4.5	6.4	1.5	5.0	7.5	18	ns

NOTE:
1. These typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.

AC WAVEFORMS

V_M = 1.5 V at $V_{CC} \geq$ 2.7 V
V_M = 0.5 • V_{CC} at V_{CC} < 2.7 V
V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.

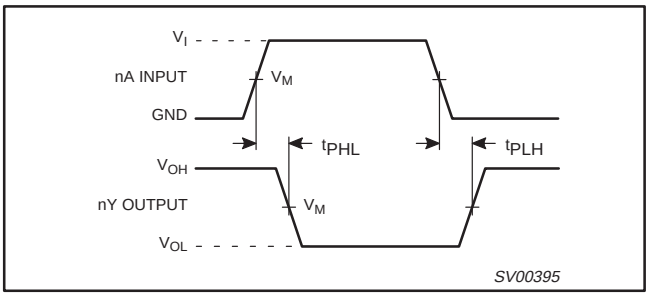
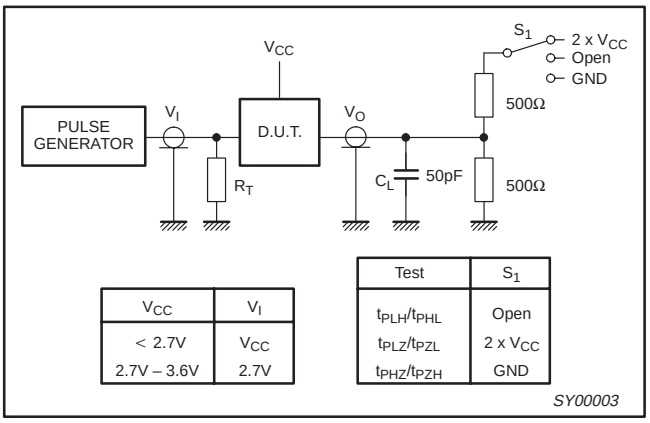


Figure 1. Input (nA) to output (nY) propagation delays.

TEST CIRCUIT



V_{CC}	V_I
< 2.7V	V_{CC}
2.7V – 3.6V	2.7V

Test	S_1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 x V_{CC}
t_{PHZ}/t_{PZH}	GND

Figure 2. Load circuitry for switching times.

APPLICATION INFORMATION

All values given are typical unless otherwise specified.

Note to Figure 7: $f = \frac{1}{T} \approx \frac{1}{0.8 \times RC}$

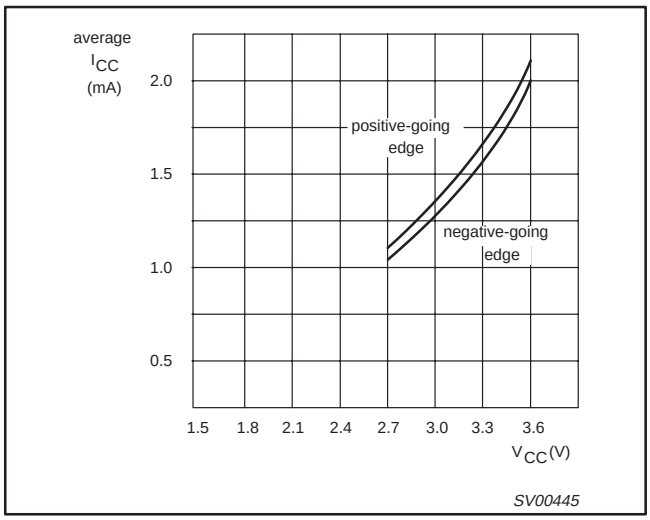


Figure 3. Average I_{CC} for LVC Schmitt-trigger devices; linear change of V_i between 0.8 V to 2.0 V.

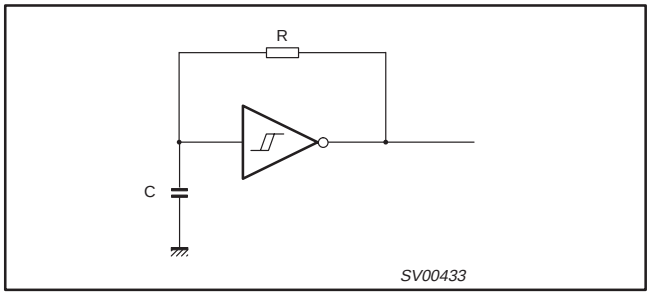
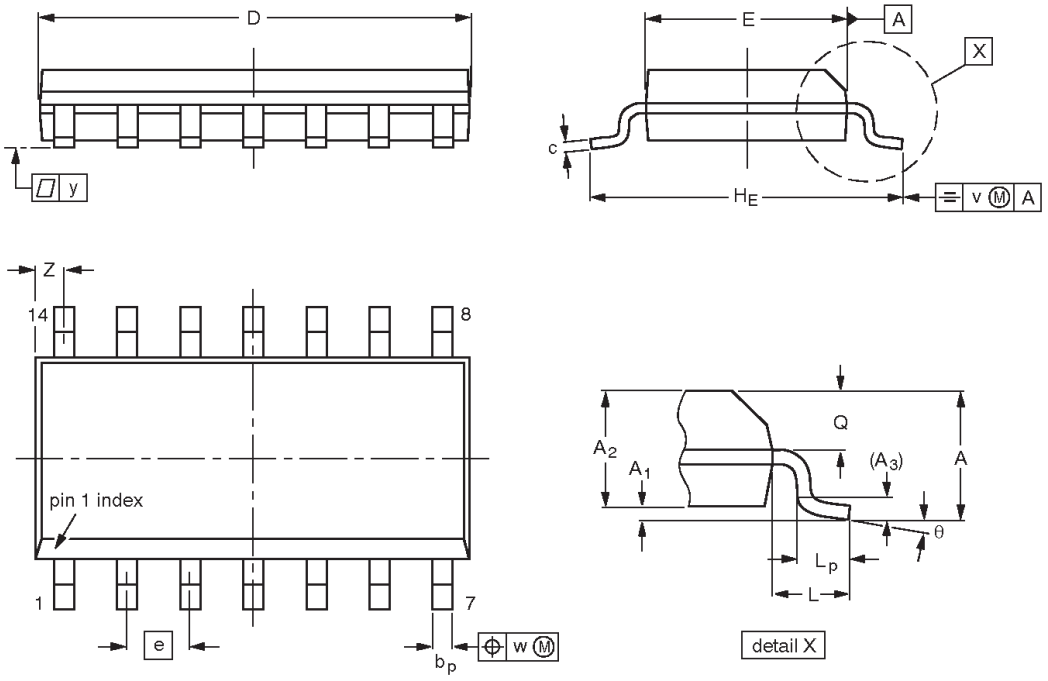
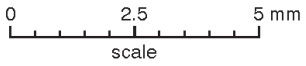


Figure 4. Relaxation oscillator using the LVC14.

SO14: plastic small outline package; 14 leads; body width 3.9 mm **SOT108-1**





DIMENSIONS (inch dimensions are derived from the original mm dimensions)

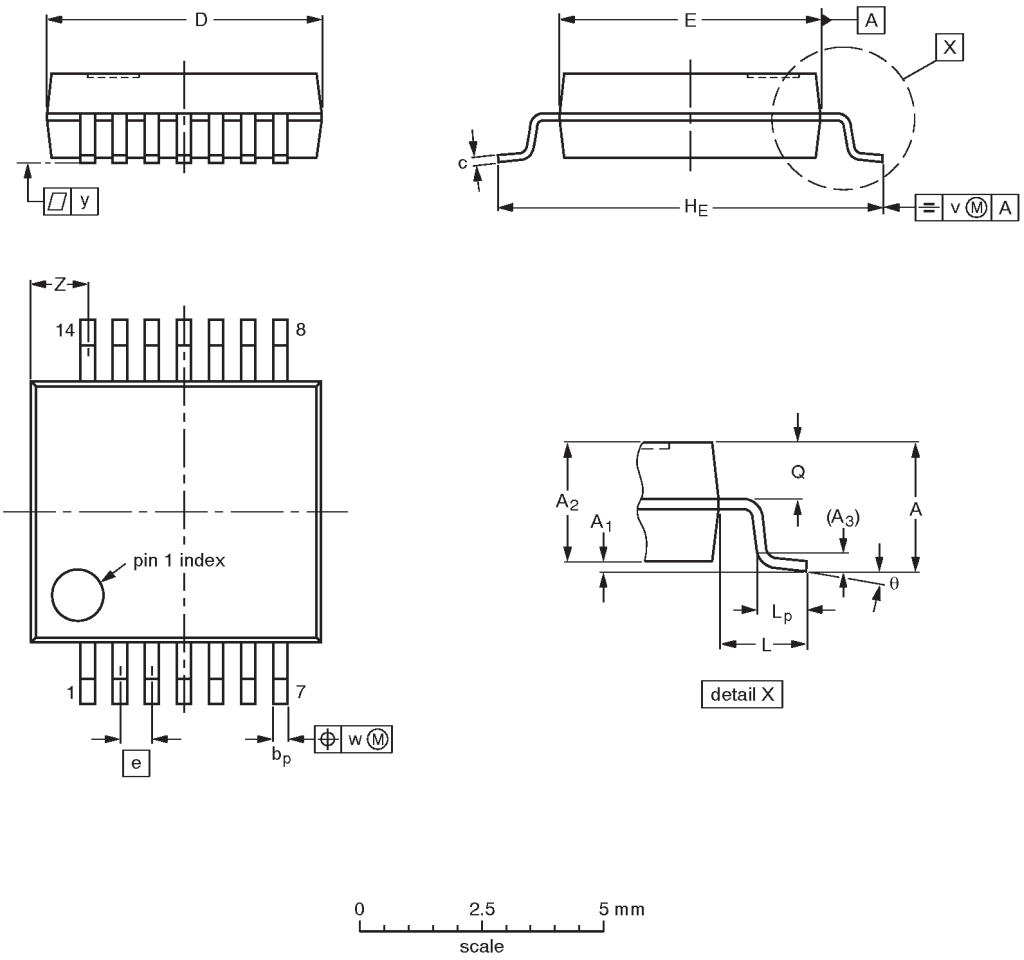
UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8^o 0^o
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.35 0.34	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT108-1	076E06S	MS-012AB				~~95-01-23~~ 97-05-22

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm **SOT337-1**



DIMENSIONS (mm are the original dimensions)

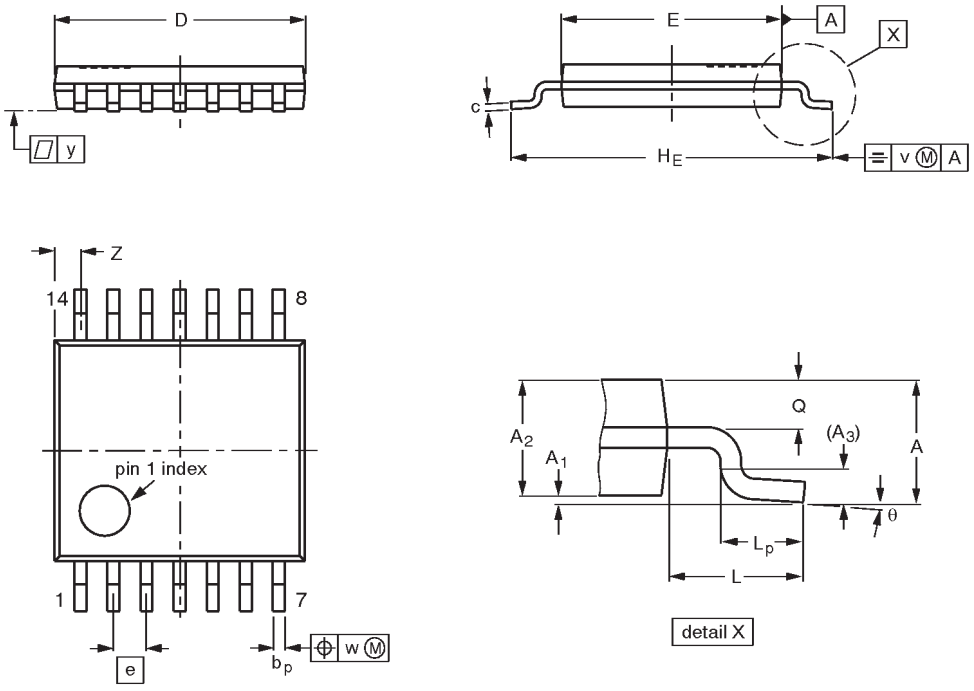
UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (1)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.4 0.9	8° 0°

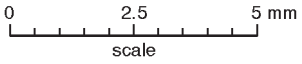
Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT337-1		MO-150AB				~~95-02-04~~ 96-01-18

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm **SOT402-1**





DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT402-1		MO-153				~~94-07-12~~ 95-04-04

Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

[1] Please consult the most recently issued datasheet before initiating or completing a design.

Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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